

HOSTAFORM® MT®8F01

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Hostaform® MT®8F01 is a medium viscosity grade filled with low level of polytetrafluoroethylene (PTFE). Hostaform® MT®8F01 is designed for use in wear applications against plastics, metal, glass or ceramic mating surfaces where silicone lubricants can not be tolerated.

Hostaform® MT®8F01 is a special grade developed for medical industry applications and complies with:

- CFR 21 (177.2470) of the Food and Drug Administration (FDA) and is listed in the Drug Master File (DMF 11559) and the Device Master File (MAF 1079)
- the corresponding EU and national registry regulatory requirements
- biocompatibility in tests corresponding to USP <88> Class VI/ISO 10993
- low residual monomers
- no animal-derived constituents

Product information

Resin Identification	POM+PTFE	ISO 1043
Part Marking Code	>POM+PTFE<	ISO 11469

Rheological properties

Melt volume-flow rate	7.9 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile modulus	2600 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	58 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	28 %	ISO 527-1/-2
Charpy notched impact strength, 23 °C	5.2 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.38 ^[C]	
[C]: Calculated		

Thermal properties

Melting temperature, 10 °C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	102 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120 E-6/K	ISO 11359-1/-2

Physical/Other properties

Density	1440 kg/m ³	ISO 1183
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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C

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Min. melt temperature	180 °C
Max. melt temperature	200 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa
Ejection temperature	134 °C

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction

Additional information

Processing Notes

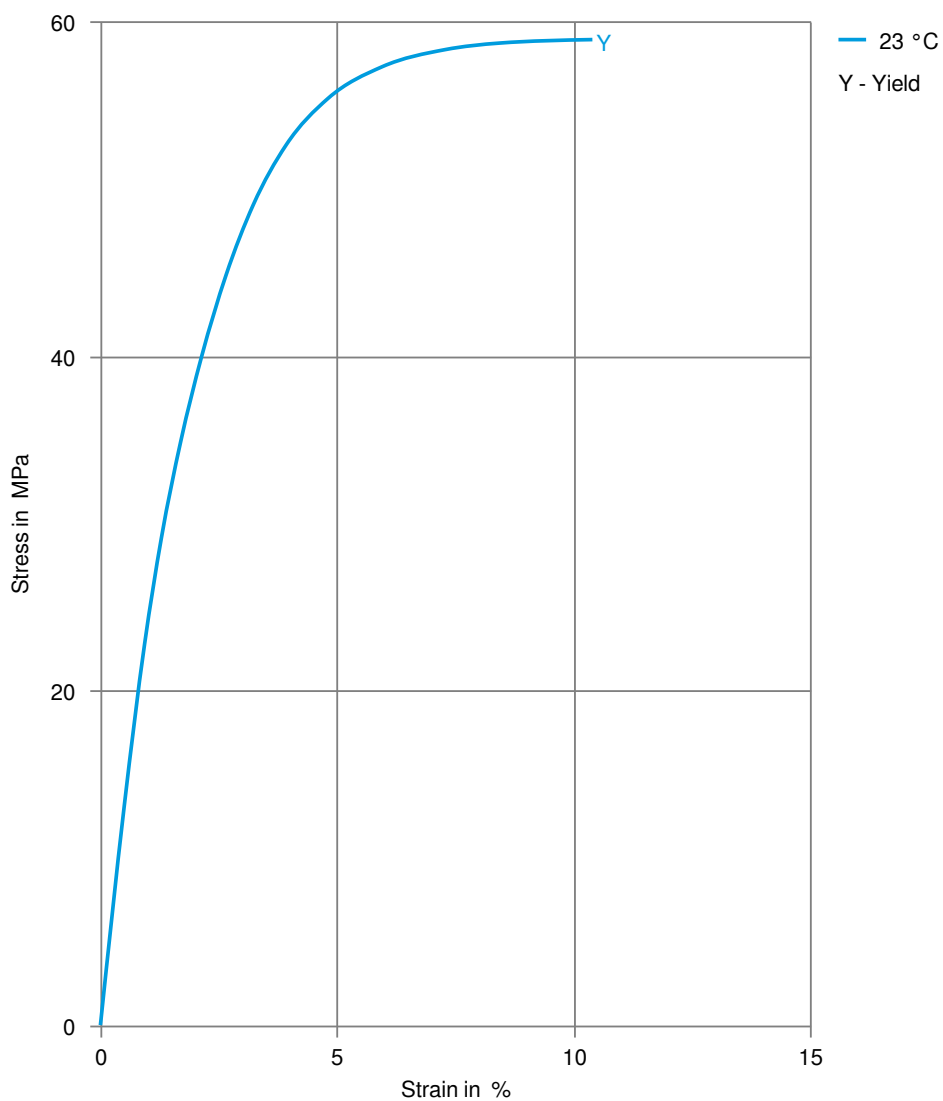
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling, drying may be necessary to prevent splay and odor problems.

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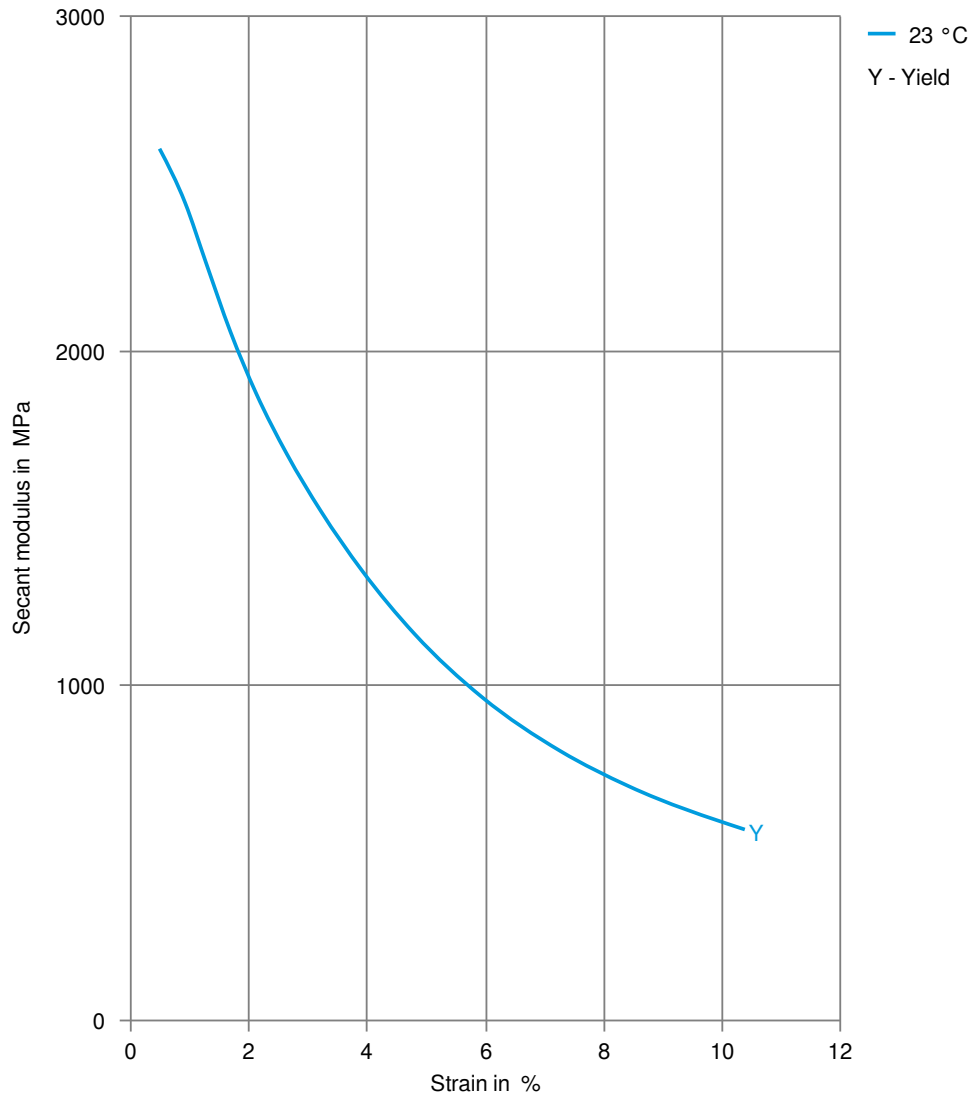
Stress-strain



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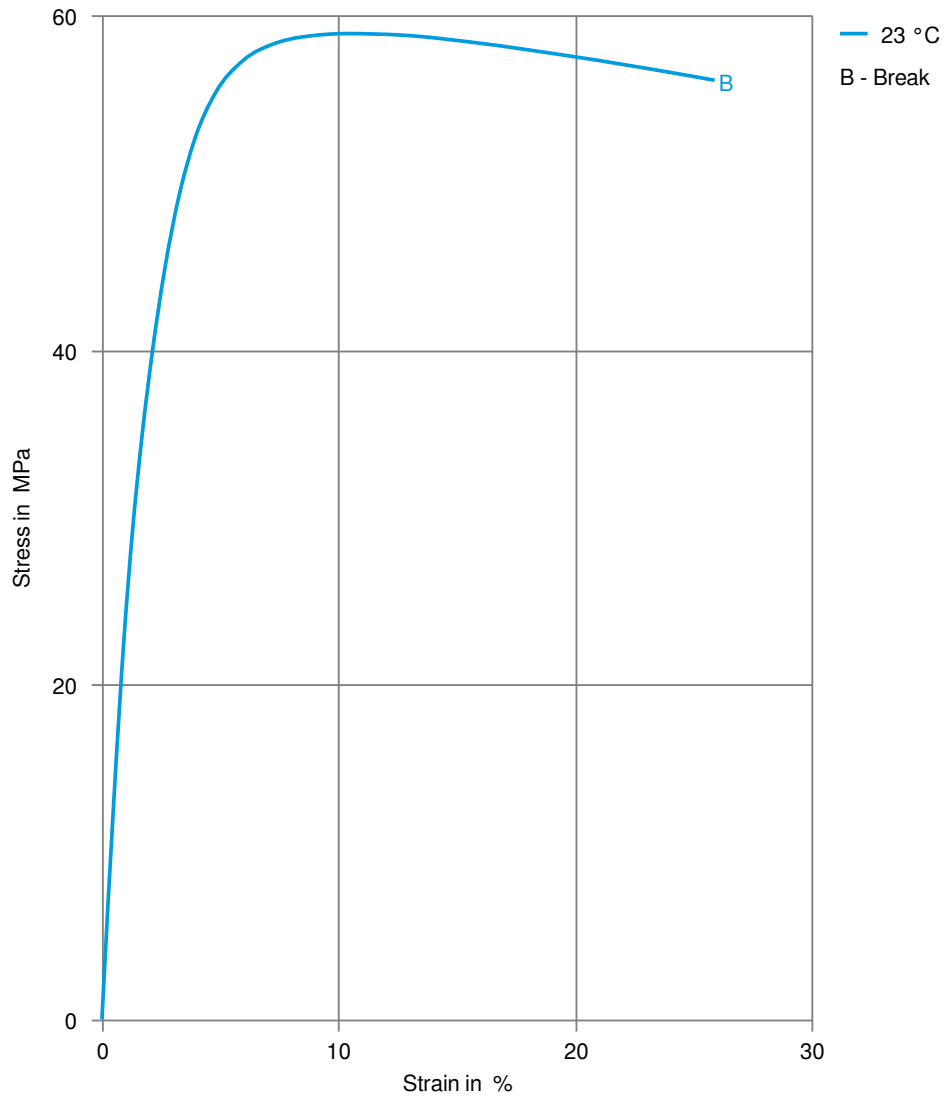
Secant modulus-strain



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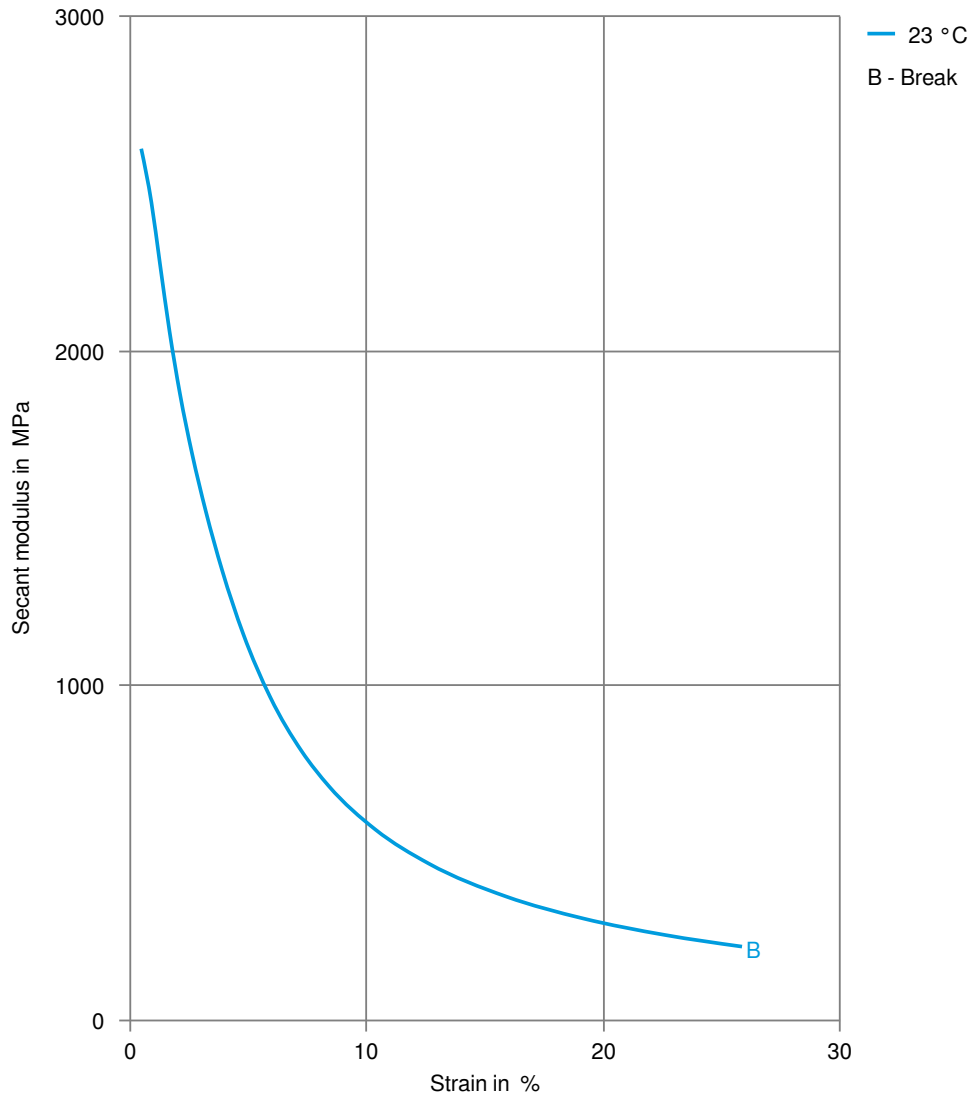
Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min



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